

## Hometaxial-Base High-Current Silicon N-P-N Transistor

Rugged High-Voltage Device for Applications in Industrial and Commercial Equipment

*Features:*

- High dissipation capability — 150 W
- 8-A specification for  $h_{FE}$ ,  $V_{BE}$ , and  $V_{CE(sat)}$
- $V_{CEX}$  — 160 V min.
- Low saturation voltage with high beta

RCA-43104\* is a hometaxial-base silicon n-p-n transistor intended for a wide variety of high-voltage high-current applications. Typical applications include power-switching circuits, audio amplifiers, series- and shunt-regulator driver and output stages, dc-to-dc converters, inverters, and solenoid (hammer)/relay driver service. The 43104 employs the popular JEDEC TO-3 package.

\* Formerly type RCA508.

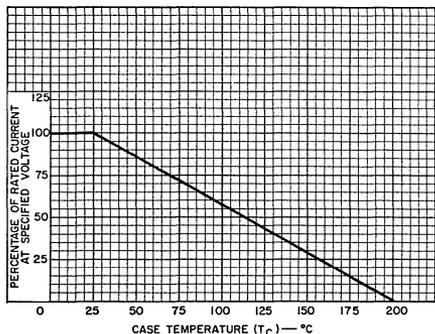


Fig. 1 — Current derating curve.

**MAXIMUM RATINGS, Absolute-Maximum Values:**

COLLECTOR-TO-BASE VOLTAGE .....	$V_{CBO}$	160	V
COLLECTOR-TO-EMITTER VOLTAGE:			
With base open .....	$V_{CEO}$	140	V
With reverse bias ( $V_{BE}$ ) of $-1.5$ V .....	$V_{CEX}$	160	V
EMITTER-TO-BASE VOLTAGE .....	$V_{EBO}$	7	V
COLLECTOR CURRENT:	$I_C$		
Continuous .....		16	A
Peak .....		30	A
BASE CURRENT:	$I_B$		
Continuous .....		4	A
Peak .....		15	A
TRANSISTOR DISSIPATION:	$P_T$		
At case temperatures up to $25^{\circ}C$ .....		150	W
At case temperatures above $25^{\circ}C$ .....		See Fig. 1	
TEMPERATURE RANGE:			
Storage & Operating (Junction) .....		$-65$ to $+200$	$^{\circ}C$
PIN TEMPERATURE (During Soldering):			
At distances $\geq 1/32$ in. (0.8 mm) from case for 10 s max. ....		230	$^{\circ}C$

ELECTRICAL CHARACTERISTICS, At Case Temperature ( $T_C$ ) = 25°C Unless Otherwise Specified

CHARACTERISTIC	SYMBOL	TEST CONDITIONS							LIMITS		UNITS
		VOLTAGE V dc				CURRENT A dc			43104		
		V <sub>CB</sub>	V <sub>CE</sub>	V <sub>EB</sub>	V <sub>BE</sub>	I <sub>C</sub>	I <sub>E</sub>	I <sub>B</sub>	Min.	Max.	
Collector-Cutoff Current: With emitter open	I <sub>CBO</sub>	140					0		–	2	mA
With base-emitter junction reverse-biased	I <sub>CEX</sub>		140		–1.5				–	2	mA
With base-emitter junction reverse-biased and T <sub>C</sub> = 150°C	I <sub>CEX</sub>		140		–1.5				–	10	mA
With base open	I <sub>CEO</sub>		120				0	–	–	10	mA
Emitter-Cutoff Current	I <sub>EBO</sub>			7		0			–	5	mA
DC Forward-Current Transfer Ratio	h <sub>FE</sub>		4 4			8 <sup>a</sup> 16 <sup>a</sup>			15 5	60 –	
Collector-to-Emitter Sustaining Voltage: With base-emitter junction reverse- biased (R <sub>BE</sub> = 100 Ω)	V <sub>CEX(sus)</sub>				–1.5	0.1			160	–	V
With external base-to-emitter resistance (R <sub>BE</sub> ) = 100 Ω	V <sub>CER(sus)</sub>					0.2 <sup>a</sup>			150	–	V
With base open	V <sub>CEO(sus)</sub>					0.2 <sup>a</sup>	0	140	–	–	V
Base-to-Emitter Voltage	V <sub>BE</sub>		4			8 <sup>a</sup>			–	2.2	V
Collector-to-Emitter Saturation Voltage	V <sub>CE(sat)</sub>					8 <sup>a</sup> 16 <sup>a</sup>	0.8 3.2		– –	1.4 4	V
Second-Breakdown Collector Current: With base forward-biased and 1-s nonrepetitive pulse	I <sub>S/b</sub> <sup>b</sup>		60						2.5	–	A
Second-Breakdown Energy: With base reverse-biased and L = 40 mH, R <sub>BE</sub> = 100 Ω	E <sub>S/b</sub> <sup>c</sup>				–1.5	2.5			0.125	–	J
Magnitude of Common-Emitter, Small-Signal, Short-Circuit, Forward-Current Transfer Ratio (f = 50 kHz)	h <sub>fe</sub>		4			1			4	–	
Common-Emitter, Small-Signal, Short-Circuit, Forward-Current Transfer Ratio (f = 1 kHz)	h <sub>fe</sub>		4			1			40	–	
Thermal Resistance: Junction-to-Case	R <sub>θJC</sub>								–	1.17	°C/W

<sup>a</sup> Pulsed; pulse duration = 300 μs, rep. rate = 60 Hz, duty factor ≤ 2%.

<sup>b</sup> I<sub>S/b</sub> is defined as the current at which second breakdown occurs at a specified collector voltage with the emitter-base junction forward-biased for transistor operation in the active region.

<sup>c</sup> E<sub>S/b</sub> is defined as the energy at which second breakdown occurs under specified reverse-bias conditions. E<sub>S/b</sub> = 1/2LI<sup>2</sup> where L is a series load or leakage inductance and I is the peak collector current.

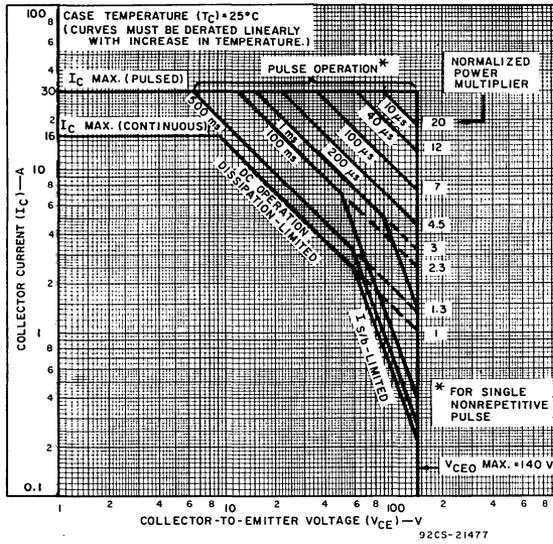


Fig. 2 — Maximum operating areas.

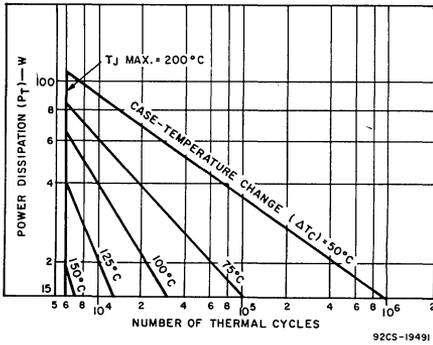


Fig. 3 — Thermal-cycling rating chart.

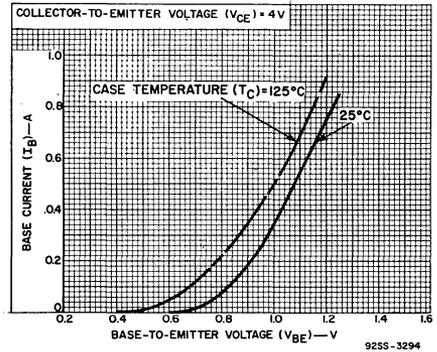


Fig. 4 — Typical input characteristics.

TERMINAL CONNECTIONS

- Pin 1 — Base
- Pin 2 — Emitter
- Case — Collector
- Mounting Flange — Collector

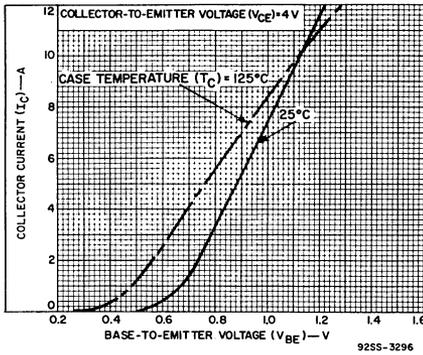


Fig. 5 - Typical transfer characteristics.

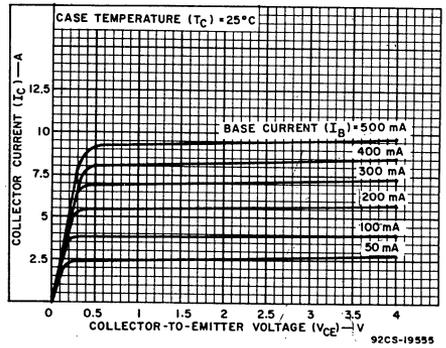


Fig. 6 - Typical output characteristics.

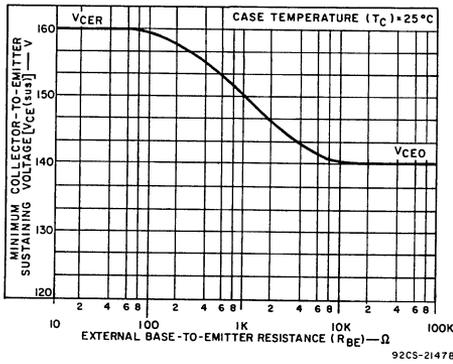


Fig. 7 - Sustaining voltage vs. base-to-emitter resistance.

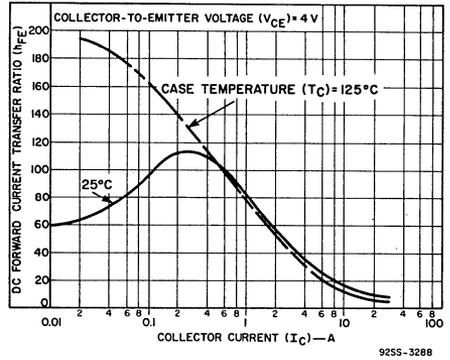


Fig. 8 - Typical dc beta characteristics.

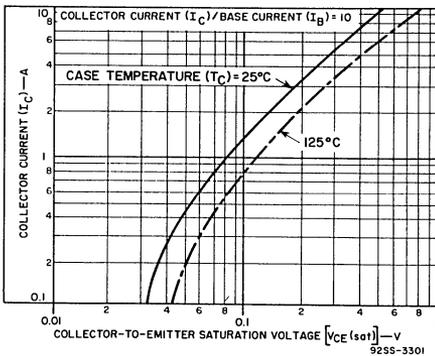


Fig. 9 - Typical saturation-voltage characteristics.

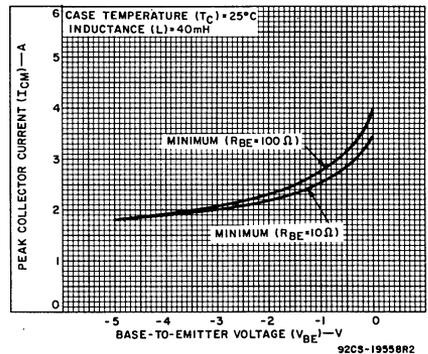


Fig. 10 - Reverse-bias second-breakdown characteristics.